

Electronic Patent Application Fee Transmittal

Application Number:	10803464			
Filing Date:	18-Mar-2004			
Title of Invention:	MULTI-FLIP CHIP ON LEAD FRAME ON OVER MOLDED IC PACKAGE AND METHOD OF ASSEMBLY			
First Named Inventor/Applicant Name:	Jonathan A. Noquil			
Filer:	Ronald S. Kareken/Penny Clements			
Attorney Docket Number:	90065.001400/.67130.00			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	1	3	3
Total in USD (\$)				1703